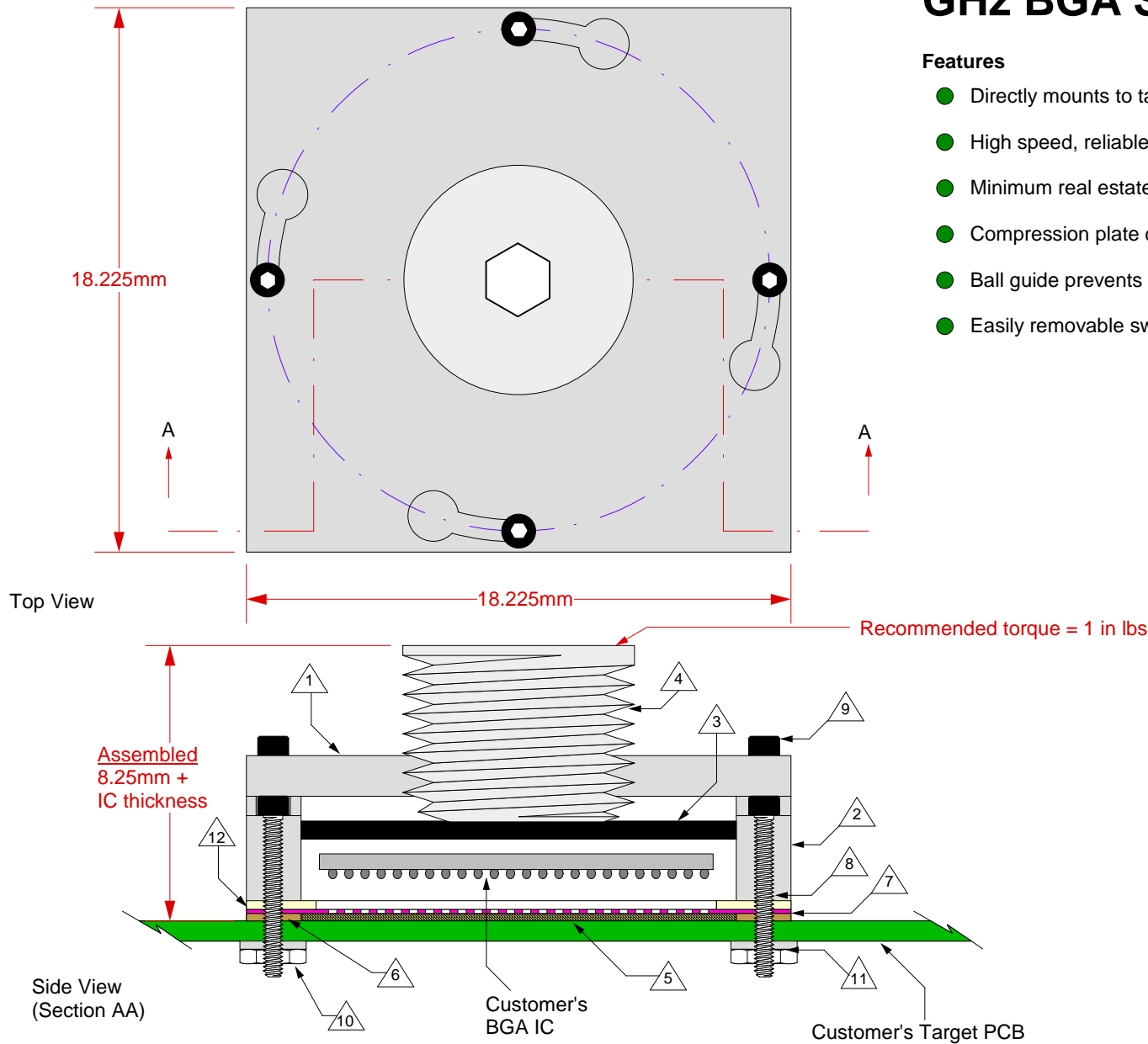



GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

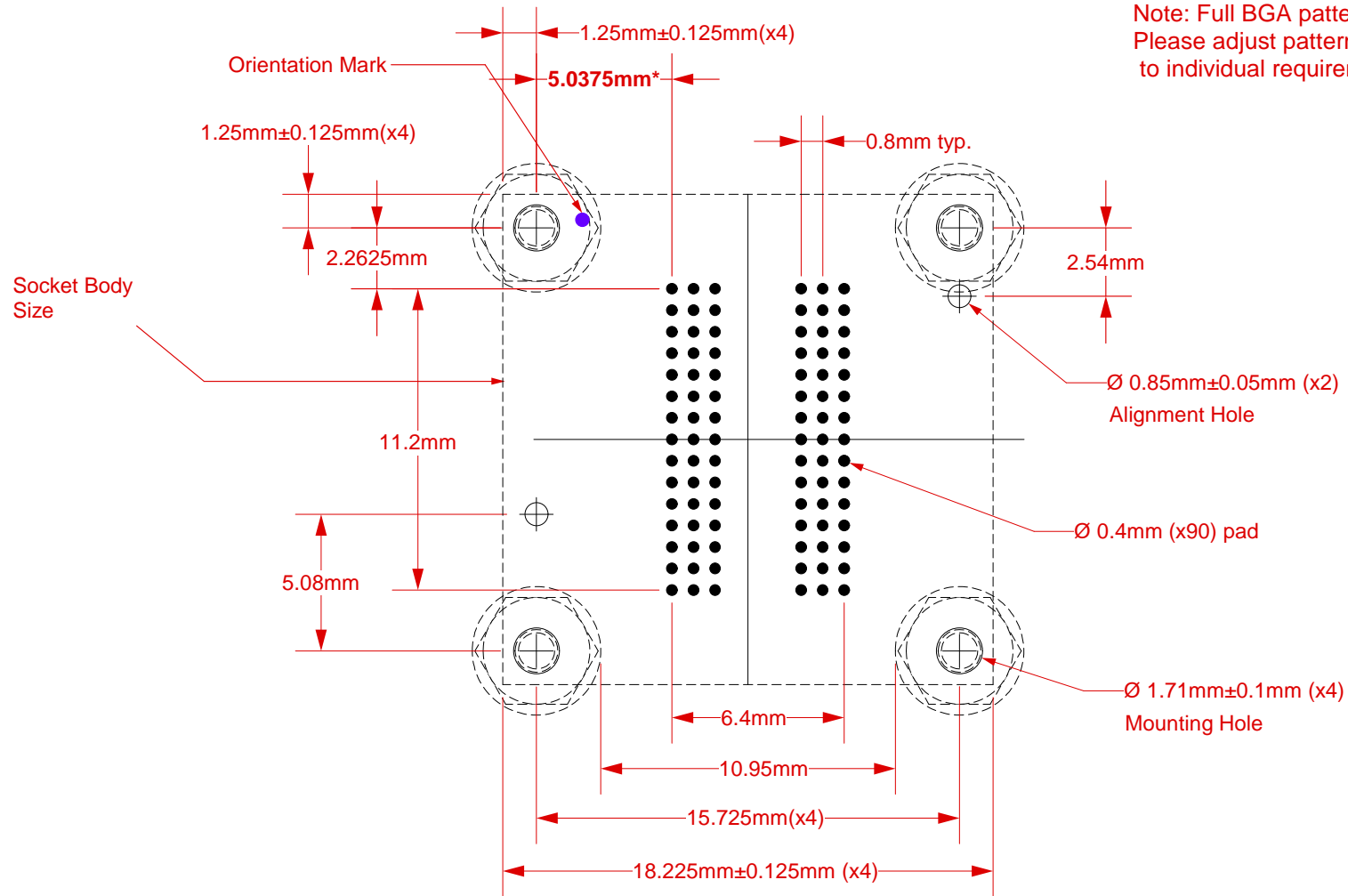


- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 4.76mm long.
- 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.
- 12 IC guide: Torlon

	SG-BGA-6373 Drawing	Status: Released	Scale: -	Rev: B
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		File: SG-BGA-6373 Dwg.mcd	Modified: 04/16/14, DH	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is *not* symmetrical with respect to the mounting holes.**



Target PCB Recommendations


Total thickness: 1.6mm min.

Plating: Gold or Solder finish

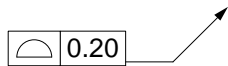
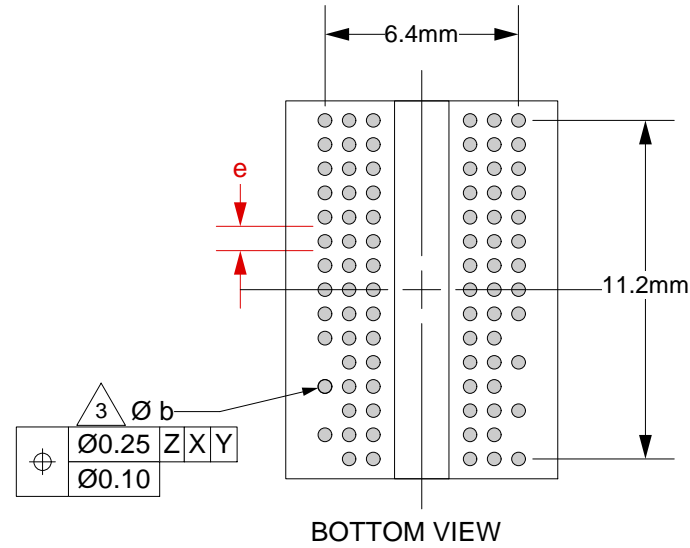
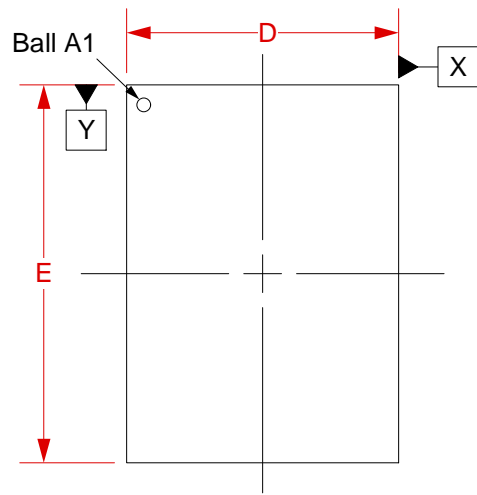
PCB Pad height: Same or higher than solder mask

NOTE: backing plate may be required based on end user's application

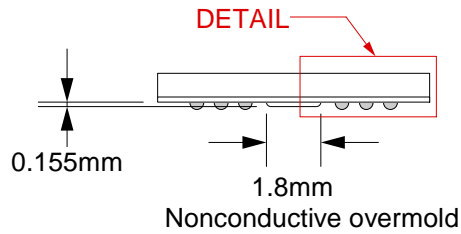
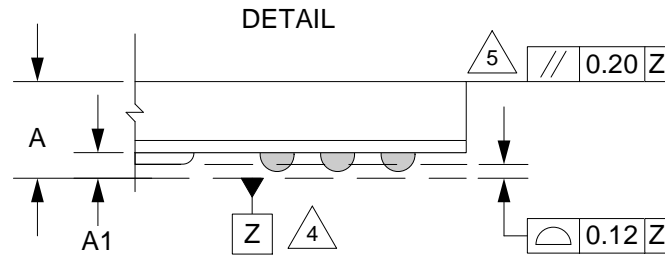
Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SG-BGA-6373 Drawing		Status: Released	Scale: 4:1	Rev: B
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			File: SG-BGA-6373 Dwg.mcd Modified: 04/16/14, DH	

Compatible BGA Spec




TOP VIEW

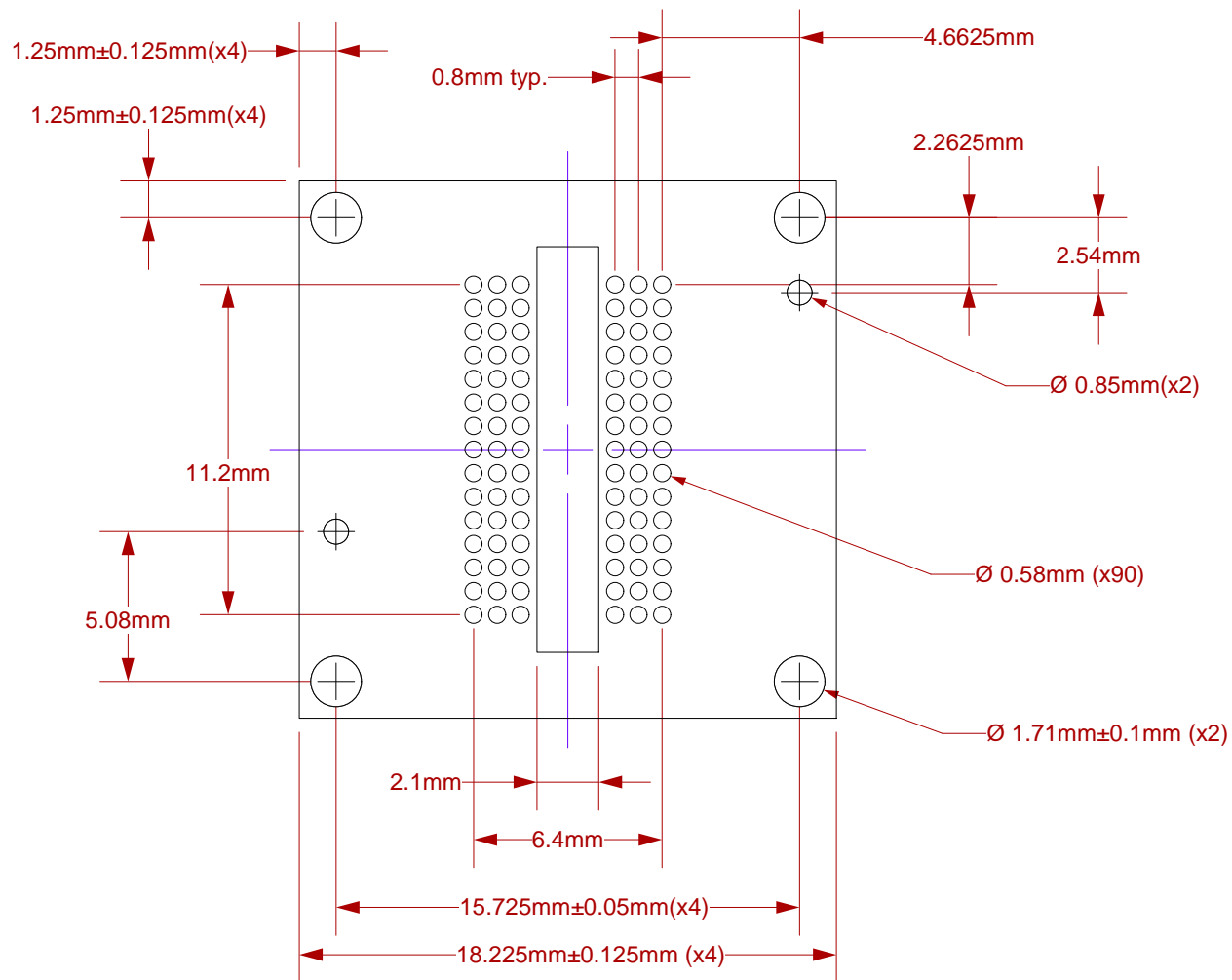


- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.


DIM	MIN	MAX
A		1.2
A1	0.25	
b		0.45
D	8.90	9.10
E	12.4	12.6
e	0.80 BSC	

Array 9x15

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		File: SG-BGA-6373Dwg.mcd	Modified: 04/16/14, DH	



Description: Ball Guide

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		Drawing: S. Huang		Date: 12/20/2012
		File: SG-BGA-6373 Dwg.mcd		Modified: 04/16/14, DH

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.